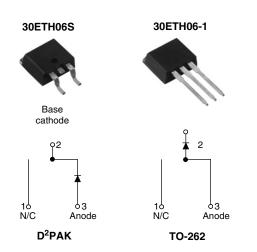


### Vishay High Power Products

# Hyperfast Rectifier, 30 A FRED Pt<sup>™</sup>



PRODUCT SUMMARY				
t <sub>rr</sub> (typical)	28 ns			
I <sub>F(AV)</sub>	30 A			
V <sub>R</sub>	600 V			

#### FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- Low leakage current
- 125 °C operating junction temperature
- Dual diode center tap
- Designed and qualified for industrial level

### **DESCRIPTION/APPLICATIONS**

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC-DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	V <sub>RRM</sub>		600	V
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 103 °C	30	А
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	200	A
Operating junction and storage temperatures	$T_J,T_Stg$		- 65 to 175	°C

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	600	-	-		
Forward voltage V <sub>F</sub>	N	I <sub>F</sub> = 30 A	-	2.0	2.6	V	
	۷F	I <sub>F</sub> = 30 A, T <sub>J</sub> = 150 °C	-	1.34	1.75		
Reverse leakage current I <sub>R</sub>	$V_R = V_R$ rated	-	0.3	50			
	'R	$T_J = 150 \ ^{\circ}C, \ V_R = V_R \text{ rated}$	-	60	500	μΑ	
Junction capacitance	CT	V <sub>R</sub> = 600 V -		33	-	pF	
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body - 8.0 -			-	nH	

# 30ETH06S/30ETH06-1

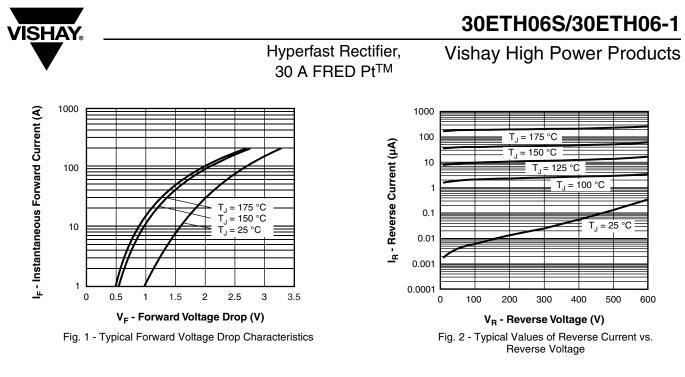
# Vishay High Power Products

### Hyperfast Rectifier, 30 A FRED Pt<sup>™</sup>



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
		$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		-	28	35	
Reverse recovery time t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	31	-	ns	
		T <sub>J</sub> = 125 °C		-	77	-	
Peak recovery current I <sub>RRM</sub>		T <sub>J</sub> = 25 °C	I <sub>F</sub> = 30 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	3.5	-	A
	IRRM	T <sub>J</sub> = 125 °C		-	7.7	-	
Reverse recovery charge Q <sub>rr</sub>	0	T <sub>J</sub> = 25 °C		-	65	-	nC
	T <sub>J</sub> = 125 °C		-	345	-		

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 65	-	175	°C
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	0.7	1.1	
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-	
Maiaht			-	2.0	-	g
Weight			-	0.07	-	OZ.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf ⋅ cm (lbf ⋅ in)
Mandaha a danaha a		Case style D <sup>2</sup> PAK	30ETH06S			
Marking device		Case style TO-262	30ETH06-1			



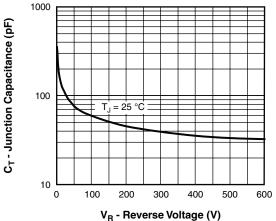


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

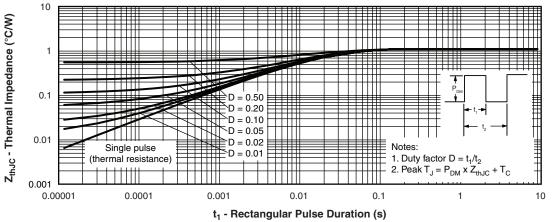
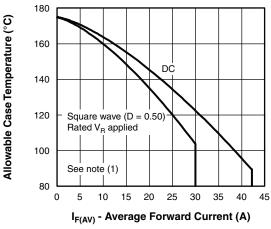


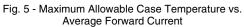
Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

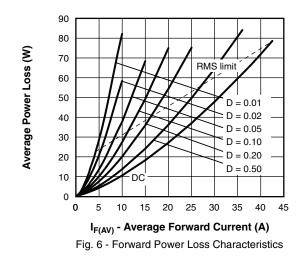
# 30ETH06S/30ETH06-1

## **Vishay High Power Products**

Hyperfast Rectifier, 30 A FRED Pt<sup>™</sup>

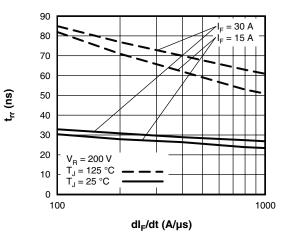






#### Note

 $^{(1)} \mbox{ Formula used: } T_C = T_J - (Pd + Pd_{REV}) \ x \ R_{thJC}; \\ Pd = \mbox{ Forward power loss } = I_{F(AV)} \ x \ V_{FM} \ at \ (I_{F(AV)}/D) \ (see \ fig. \ 6); \\ Pd_{REV} = \mbox{ Inverse power loss } = V_{R1} \ x \ I_R \ (1 - D); \ I_R \ at \ V_{R1} = \ Rated \ V_R$ 



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Fig. 7 - Typical Reverse Recovery Time vs. dI<sub>F</sub>/dt

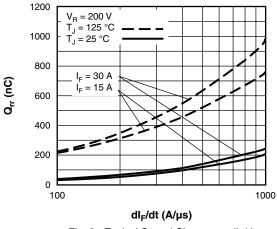


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt



### Hyperfast Rectifier, 30 A FRED Pt<sup>TM</sup>

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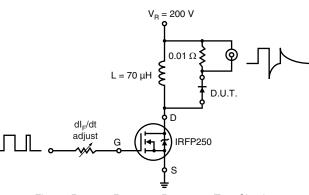


Fig. 9 - Reverse Recovery Parameter Test Circuit

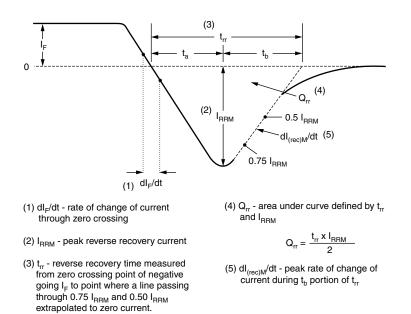
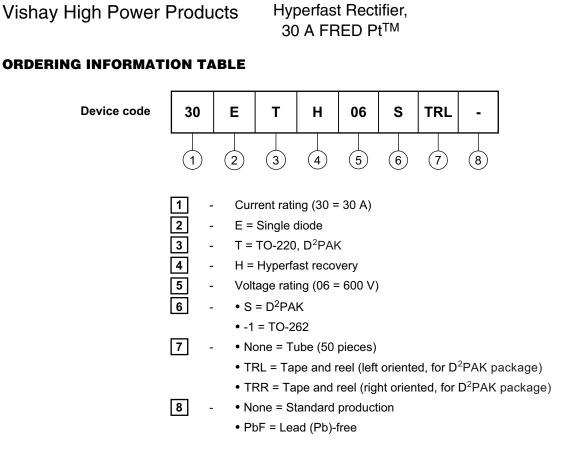


Fig. 10 - Reverse Recovery Waveform and Definitions

## 30ETH06S/30ETH06-1



LINKS TO RELATED DOCUMENTS				
Dimensions http://www.vishay.com/doc?95014				
Part marking information	http://www.vishay.com/doc?95008			
Packaging information	http://www.vishay.com/doc?95032			



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